

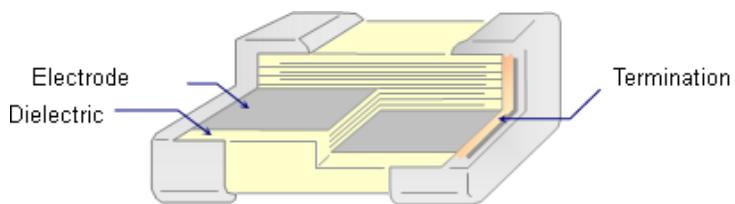
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E Standard Number

E3	1.0				2.2				4.7															
E6	1.0			1.5		2.2			3.3		4.7		6.8											
E12	1.0	1.2	1.5	1.8	2.2	2.7	3.3	3.9	4.7	5.6	6.8	8.2												
E24	1.0	1.1	1.2	1.3	1.5	1.6	1.8	2.0	2.2	2.4	2.7	3.0	3.3	3.6	3.9	4.3	4.7	5.1	5.6	6.2	6.8	7.5	8.2	9.1

Structure



Ordering Code

C 1005 NP0 101 J G T S △

PRODUCT CODE

C = MLCC

SIZE in mm (EIA CODE, in inch)

0402(01005)	0603(0201)	1005 (0402)	1608 (0603)	2012 (0805)
3216 (1206)	3225(1210)	4520 (1808)	4532 (1812)	

T. C.

NP0: $0 \pm 30\text{ppm}/^\circ\text{C}$ -55°C to +125°C X5R: $\pm 15\%$ -55°C to +85°C
 X7R: $\pm 15\%$ X7S: $\pm 22\%$ X7T: $+22\%/-33\%$ X7U: $+22\%/-56\%$ -55°C to +125°C
 X6S: $\pm 22\%$ -55°C to +105°C Y5V: $+22\%/-82\%$ -30°C to +85°C

CAPACITANCE CODE

Expressed in pico-farads and identified by a three-digit number.

First two digits represent significant figures.

Last digit specifies the number of zeros.

(Use 9 for 1.0 through 9.9pF ; Use 8 for 0.20 through 0.99pF)

Examples:

Code	Cap (pF)
478	0.47
229	2.2
101	100
102	1000

TOLERANCE CODE

A: $\pm 0.05\text{pF}$	B: $\pm 0.1\text{pF}$	C: $\pm 0.25\text{pF}$	D: $\pm 0.5\text{pF}$	F: $\pm 1\%$	G: $\pm 2\%$
J: $\pm 5\%$	K: $\pm 10\%$	M: $\pm 20\%$	Z: $+80/-20\%$		

VOLTAGE CODE

B: 4V	C: 6.3V	D: 10V	E: 16V	F: 25V	N: 35V	G: 50V	H: 100V
J: 200V	K: 250V	L: 500V	M: 630V	P: 1KV	Q: 2KV	R: 3KV	S: 4KV

PACKAGING CODE

T: Paper tape reel Ø180mm (7")

P: Embossed tape reel Ø180mm (7")

N: Paper tape reel Ø250mm (10")

D: Embossed tape reel Ø250mm (10")

A: Paper tape reel Ø330mm (13")

E: Embossed tape reel Ø330mm (13")

W: Special Packing

Application Code

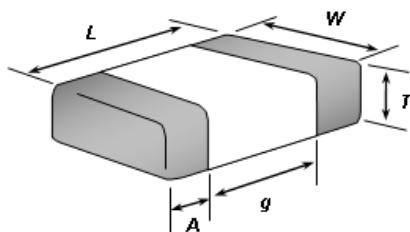
S: Standard Q: High Q/Low ESR F: Microwave A: Automotive Infotainment with AEC-Q200

Thickness Code

Code	Thick (mm)	Code	Thick(mm)	Code	Thick (mm)	Code	Thick (mm)
(blank)	Standard Thick	M	0.70	G	1.25	S	1.90
Z	0.20	D	0.80	H	1.50	--	--
A	0.30	E	0.85	L	1.60	--	--
Q	0.45	I	0.95	N	2.00	--	--
B	0.50	J	1.00	P	2.50	--	--
C	0.60	F	1.15	R	3.20	--	--

General Purpose

■ External Dimensions



TYPE		Dimension (mm)				
Size (EIA Size)	Kind	L (Length)	W (Width)	T (Max.)	g (Min)	A (Min/Max)
C0603 (0201)	Standard	0.6 ± 0.03	0.30 ± 0.03	0.33	0.15	0.10 / 0.20
	Special (1)	0.6 ± 0.05	0.30 ± 0.05	0.35		0.10 / 0.25
	Special (2)	0.6 ± 0.09	0.30 ± 0.09	0.39		
C1005 (0402)	Standard	1.0 ± 0.05	0.50 ± 0.05	0.55	0.30	0.15 / 0.35
	Special (1)	1.0 ± 0.10	0.50 ± 0.10	0.60		
	Special (2)	1.0 ± 0.15	0.50 ± 0.15	0.65		
	Special (3)	1.0 ± 0.20	0.50 ± 0.20	0.70		
C1608 (0603)	Standard	1.6 ± 0.10	0.80 ± 0.10	0.90	0.50	0.25 / 0.65
	Special (1)	1.6 ± 0.15	0.80 ± 0.15	0.95		
	Special (2)	1.6 ± 0.20	0.80 ± 0.20	1.00		
C2012 (0805)	Standard	2.0 ± 0.15	1.25 ± 0.15	1.45	0.70	0.25 / 0.75
	Special (1)	2.0 ± 0.20	1.25 ± 0.20	1.45		
C3216 (1206)	Standard	3.2 ± 0.15	1.60 ± 0.15	1.80	1.50	0.25 / 0.75
	Special (1)	3.2 ± 0.20	1.60 ± 0.20	1.90		
	Special (2)	3.2 ± 0.30	1.60 ± 0.30	1.90		
C3225 (1210)	Standard	3.2 ± 0.30	2.50 ± 0.20	2.80	1.50	0.3 / 0.90
	Special (1)	3.2 ± 0.40	2.50 ± 0.30	2.80		

For special parts, please see the "Part Number & Characteristic" for detail specification.

- C3216NP0_S Series (EIA1206)

RV	DARFON P/N	Darfon P/N 2	Measuring Condition	Capacitance		Available Tolerance	Thick. (mm)	Tolerance(mm)		DF (max.)	Standard Packing
				Value	Unit			L/W	Thick.		
50V	C3216NP0123JGPS	C3216NP0123JGP	1V, 1kHz	12	nF	±5%	1.60	±0.30	±0.30	0.10%	Embossed, 2Kpcs
	C3216NP0153JGPS	C3216NP0153JGP	1V, 1kHz	15	nF	±5%	1.60	±0.30	±0.30	0.10%	
	C3216NP0183JGPS	C3216NP0183JGP	1V, 1kHz	18	nF	±5%	1.60	±0.30	±0.30	0.10%	
	C3216NP0223JGPS	C3216NP0223JGP	1V, 1kHz	22	nF	±5%	1.60	±0.30	±0.30	0.10%	
	C3216NP0273JGPS	C3216NP0273JGP	1V, 1kHz	27	nF	±5%	1.60	±0.30	±0.30	0.10%	
	C3216NP0333JGPS	C3216NP0333JGP	1V, 1kHz	33	nF	±5%	1.60	±0.30	±0.30	0.10%	
	C3216NP0393JGPS	C3216NP0393JGP	1V, 1kHz	39	nF	±5%	1.60	±0.30	±0.30	0.10%	
16V	C3216NP0473JGPS	C3216NP0473JGP	1V, 1kHz	47	nF	±5%	1.15	±0.20	±0.20	0.10%	Embossed, 3Kpcs
	C3216NP0123JEPS	C3216NP0123JEP	1V, 1kHz	12	nF	±5%	1.60	±0.30	±0.30	0.10%	
	C3216NP0153JEPS	C3216NP0153JEP	1V, 1kHz	15	nF	±5%	1.60	±0.30	±0.30	0.10%	
	C3216NP0183JEPS	C3216NP0183JEP	1V, 1kHz	18	nF	±5%	1.60	±0.30	±0.30	0.10%	
	C3216NP0223JEPS	C3216NP0223JEP	1V, 1kHz	22	nF	±5%	1.60	±0.30	±0.30	0.10%	
	C3216NP0273JEPS	C3216NP0273JEP	1V, 1kHz	27	nF	±5%	1.60	±0.30	±0.30	0.10%	
	C3216NP0333JEPS	C3216NP0333JEP	1V, 1kHz	33	nF	±5%	1.60	±0.30	±0.30	0.10%	
16V	C3216NP0393JEPS	C3216NP0393JEP	1V, 1kHz	39	nF	±5%	1.60	±0.30	±0.30	0.10%	

□ Tolerance Code: F=±1%, G=±2%, J=±5%; Special tolerance on the request.

● C3225X5R Series (EIA1210)

RV	DARFON P/N	Darfon P/N 2	Measuring Condition	Capacitance		Available Tolerance	Thick. (mm)	Tolerance(mm)		DF (max.)	Standard Packing	Test Spec.
				Value	Unit			L/W	Thick.			
50V	C3225X5R106 GPS	C3225X5R106 GP	1V , 1kHz	10	uF	±10% , ±20%	2.50	±0.30/±0.20	±0.20	5.0%	Embossed, 1Kpcs	(II)
35V	C3225X5R106 NPS	C3225X5R106 NP	1V , 1kHz	10	uF	±10% , ±20%	2.50	±0.30/±0.20	±0.20	5.0%	Embossed, 1Kpcs	(I)
25V	C3225X5R475 FWS	C3225X5R475 FW	1V , 1kHz	4.7	uF	±10% , ±20%	2.00	±0.30/±0.20	±0.20	10.0%	Embossed, 1Kpcs	(I)
	C3225X5R106 FPS	C3225X5R106 FP	1V , 1kHz	10	uF	±10% , ±20%	2.00	±0.30/±0.20	±0.20	10.0%	Embossed, 2Kpcs	(I)
	C3225X5R226 FPS	C3225X5R226 FP	0.5V , 120Hz	22	uF	±10% , ±20%	2.50	±0.30/±0.20	±0.20	10.0%	Embossed, 1Kpcs	(II)
16V	C3225X5R475 EWS	C3225X5R475 EW	1V , 1kHz	4.7	uF	±10% , ±20%	2.00	±0.30/±0.20	±0.20	5.0%	Embossed, 1Kpcs	(I)
	C3225X5R106 EPS	C3225X5R106 EP	1V , 1kHz	10	uF	±10% , ±20%	2.00	±0.30/±0.20	±0.20	5.0%	Embossed, 2Kpcs	(I)
	C3225X5R226 EWS	C3225X5R226 EW	0.5V , 120Hz	22	uF	±10% , ±20%	2.50	±0.30/±0.20	±0.20	15.0%	Embossed, 0.5Kpcs	(II)
	C3225X5R476 EWS	C3225X5R476 EW	0.5V , 120Hz	47	uF	±10% , ±20%	2.50	±0.30/±0.20	±0.20	15.0%		(II)
	C3225X5R476 EPS	C3225X5R476 EP	0.5V , 120Hz	47	uF	±10% , ±20%	2.50	±0.30/±0.20	±0.20	15.0%	Embossed, 1Kpcs	(II)
	C3225X5R107MEPS	C3225X5R107MEP	0.5V , 120Hz	100	uF	±20%	2.50	±0.30	±0.30	10.0%		(II)
10V	C3225X5R226 DPS	C3225X5R226 DP	0.5V , 120Hz	22	uF	±10% , ±20%	2.50	±0.30/±0.20	±0.20	10.0%	Embossed, 1Kpcs	(II)
	C3225X5R476 DPS	C3225X5R476 DP	0.5V , 120Hz	47	uF	±10% , ±20%	2.50	±0.30/±0.20	±0.20	10.0%		(II)
	C3225X5R107MDPS	C3225X5R107MDP	0.5V , 120Hz	100	uF	±20%	2.50	±0.30/±0.20	±0.30	10.0%		(II)
6.3V	C3225X5R226 CPS	C3225X5R226 CP	0.5V , 120Hz	22	uF	±10% , ±20%	2.50	±0.30/±0.20	±0.20	10.0%	Embossed, 1Kpcs	(II)
	C3225X5R476 CPS	C3225X5R476 CP	0.5V , 120Hz	47	uF	±10% , ±20%	2.50	±0.30/±0.20	±0.20	15.0%		(II)
	C3225X5R107MCPS	C3225X5R107MCP	0.5V , 120Hz	100	uF	±20%	2.50	±0.30	±0.30	15.0%		(II)

● C4532X5R Series (EIA1812)

RV	DARFON P/N	Darfon P/N 2	Measuring Condition	Capacitance		Available Tolerance	Thick. (mm)	Tolerance(mm)		DF (max.)	Standard Packing	Test Spec.
				Value	Unit			L/W	Thick.			
50V	C4532X5R225KGPS	C4532X5R225KGP	1V , 1kHz	2.2	uF	±10%	1.60	±0.30	±0.20	10.0%	Embossed, 1Kpcs	(II)*

□ Tolerance Code: K=±10%, M=±20% ;Special tolerance on the request.;

(II)* High temperature load life test are applicable in rated voltage *100%

- C3225X6S Series (EIA1210)

RV	DARFON P/N	DARFON P/N 2	Measuring Condition	Capacitance		Available Tolerance	Thick. (mm)	Tolerance(mm)		DF (max.)	Standard Packing	Test Spec.
				Value	Unit			L/W	Thick.			
16V	C3225X6S476MEPS	C3225X6S476MEP	0.5V , 120Hz	47	uF	±20%	2.50	±0.30	±0.20	10.0%	Embossed, 1Kpcs	(II)*
6.3V	C3225X6S107MCPS	C3225X6S107MCP	0.5V , 120Hz	100	uF	±20%	2.50	±0.30	±0.30	10.0%	Embossed, 1Kpcs	(II)

□ Tolerance Code: K=±10%, M=±20% ;Special tolerance on the request.;

(II)* High temperature load life test are applicable in rated voltage *100%

- X7S Series
- C0603X7S Series (EIA0201)

RV	DARFON P/N	DARFON P/N 2	Measuring Condition	Capacitance		Available Tolerance	Thick. (mm)	Tolerance(mm		DF (max.)	Standard Packing	Test Spec.
				Value	Unit			L/W	Thick.			
10V	C0603X7S104KDT	C0603X7S104KDT	1V , 1kHz	100	nF	±10%	0.30	± 0.03	±0.03	10.0%	Paper, 15Kpcs	(II)

- C1005X7S Series (EIA0402)

RV	DARFON P/N	DARFON P/N 2	Measuring Condition	Capacitance		Available Tolerance	Thick. (mm)	Tolerance(mm		DF (max.)	Standard Packing	Test Spec.
				Value	Unit			L/W	Thick.			
10V	C1005X7S105KDT	C1005X7S105KDT	1V , 1kHz	1.0	uF	±10%	0.50	± 0.10	±0.10	10.0%	Paper, 10Kpcs	(II)
	C1005X7S225KDT	C1005X7S225KDT	1V , 1kHz	2.2	uF	±10%	0.50	± 0.20	±0.20	10.0%		(II)
	C1005X7S225KCTS	C1005X7S225KCTS	1V , 1kHz	2.2	uF	±10%	0.50	± 0.20	±0.20	10.0%		(II)

- C1608X7S Series (EIA0603)

RV	DARFON P/N	DARFON P/N 2	Measuring Condition	Capacitance		Available Tolerance	Thick. (mm)	Tolerance(mm		DF (max.)	Standard Packing	Test Spec.
				Value	Unit			L/W	Thick.			
16V	C1608X7S225KETS	C1608X7S225KET	1V , 1kHz	2.2	uF	±10%	0.80	± 0.20	±0.20	10.0%	Paper, 4Kpcs	(II)
	C1608X7S475KETS	C1608X7S475KET	1V , 1kHz	4.7	uF	±10%	0.80	± 0.20	±0.20	10.0%		(II)
	C1608X7S475KDT	C1608X7S475KDT	1V , 1kHz	4.7	uF	±10%	0.80	± 0.15	±0.15	10.0%		(II)

- C2012X7S Series (EIA0805)

RV	DARFON P/N	DARFON P/N 2	Measuring Condition	Capacitance		Available Tolerance	Thick. (mm)	Tolerance(mm		DF (max.)	Standard Packing	Test Spec.
				Value	Unit			L/W	Thick.			
50V	C2012X7S475KGPS	C2012X7S475KGP	1V , 1kHz	4.7	uF	±10%	1.25	± 0.20	±0.20	10.0%	Embossed, 3Kpcs	(II)
	C2012X7S225KFPS	C2012X7S225KFP	1V , 1kHz	2.2	uF	±10%	1.25	± 0.15	±0.15	10.0%		(II)
	C2012X7S106KFPS	C2012X7S106KFP	1V , 1kHz	10	uF	±10%	1.25	± 0.20	±0.20	10.0%		(II)*

□ Tolerance Code: K=±10%, M=±20%; Special tolerance on the request.

(II)* High temperature load life test are applicable in rated voltage *100%

- X7T Series
- C2012X7T Series (EIA0805)

RV	DARFON P/N	DARFON P/N 2	Measuring Condition	Capacitance		Available Tolerance	Thick. (mm)	Tolerance(mm)		DF (max.)	Standard Packing	Test Spec.
				Value	Unit			L/W	Thick.			
10V	C2012X7T226MDPS	C2012X7T226MDP	0.5V , 120Hz	22	uF	±20%	1.25	± 0.20	±0.20	10.0%	Embossed, 3Kpcs	(II)*

MLCC

General Purpose

□ Tolerance Code: K=±10%, M=±20%; Special tolerance on the request.

(II)* High temperature load life test are applicable in rated voltage *100%

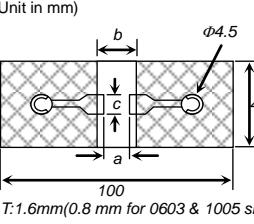
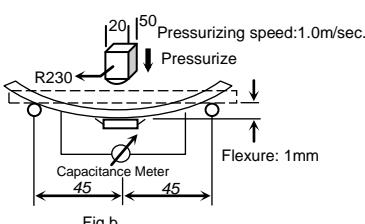
- X7U Series
- C3216X7U Series (EIA1206)

RV	DARFON P/N	DARFON P/N 2	Measuring Condition	Capacitance		Available Tolerance	Thick. (mm)	Tolerance(mm)		DF (max.)	Standard Packing	Test Spec.
				Value	Unit			L/W	Thick.			
4V	C3216X7U107MBPS	C3216X7U107MBP	0.5V , 120Hz	100	uF	±20%	1.6	± 0.30	±0.30	15.0%	Embossed, 2Kpcs	(II)*

□ Tolerance Code: K=±10%, M=±20%; Special tolerance on the request.

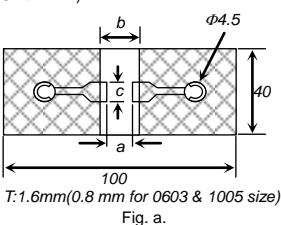
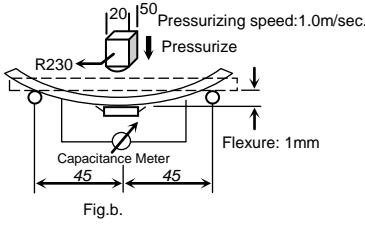
(II)* High temperature load life test are applicable in rated voltage *100%

- **Test Spec.**
- General Purpose (I)

	Item	Specification		Test Method																																
		Temp. compensation type	High dielectric constant type																																	
1	Operation Temperature Range	NP0: -55 to 125 °C X5R: -55 to 85 °C X6S: -55 to 105 °C X7R/X7S/X7T/X7U: : -55 to 125 °C Y5V: -30 to 85 °C	X5R: -55 to 85 °C X6S: -55 to 105 °C X7R/X7S/X7T/X7U: : -55 to 125 °C Y5V: -30 to 85 °C	---																																
2	Rated Voltage	Shown in the table of "Part Number & Characteristic"		The rated voltage is defined as the maximum voltage, which may be applied continuously to the capacitor.																																
3	Appearance	No defects or abnormalities.		Visual inspection																																
4	Dimensions	Within the specified dimension.		Using calipers																																
5	Dielectric Strength	No defects or abnormalities.		No failure shall be observed when 250% of the rated voltage is applied between the terminations for 1 to 5 seconds. The charge and discharge current is less than 50mA.																																
6	Insulation Resistance (I.R.)	To apply rated voltage. I.R. $\geq 10G\Omega$ or $R_c C_R \geq 500\Omega \cdot F$ (whichever is smaller)		The insulation resistance shall be measured with a DC voltage not exceeding the rated voltage at 25°C and 75%RH max, and within 1 minute of charging.																																
7	Capacitance	Within the specified tolerance * X5R, X6S, X7RS, X7S, X7T, X7U and Y5V at 1000 hours		The capacitance / D.F. shall be measured at 25°C at the frequency and voltage shown in the table of "Part Number & Characteristic".																																
8	Q/Dissipation Factor (D.F.)	NP0: If $C \leq 30pF$, DF $\leq 1/(400+20C)$, C in pF If $C > 30pF$, DF $\leq 0.1\%$.	Shown in the table of "Part Number & Characteristic"																																	
9	Capacitance Temperature Characteristics	Capacitance change NP0 within $0 \pm 30ppm/^\circ C$ under operating temperature range.	Capacitance change X5R/X7R within $\pm 15\%$ X6S/X7S within $\pm 22\%$ X7T: -33% to + 22% X7U:-56% to + 22% Y5V: -82 to + 22%	1. Temperature compensation type: The capacitance value at 25°C and 85°C shall be measured and calculated from the formula given below. $T.C. = (C_{85} - C_{25})/C_{25} \Delta T \times 10^6 (PPM/^\circ C)$ 2. High dielectric constant type: The ranges of capacitance change compared with the 25°C value over the temperature ranges shall be within the specified ranges.																																
10	Termination Strength	No removal of the terminations or marking defect.		Apply a parallel force of 5N to a PCB mounted sample for 10±1sec. *2N for 0603 (EIA 0201).																																
11	Deflection (Bending Strength)	No cracking or marking defects shall occur at 1mm deflection. Capacitance change: NP0: within $\pm 5\%$ or $\pm 0.5pF$. (whichever is larger) X5R, X6S, X7R, X7S, X7T, X7U: within $\pm 12.5\%$ Y5V: within $\pm 20\%$		Solder the capacitor to the test jig (glass epoxy boards) shown in Fig.a using a SAC305(Sn96.5Ag3.0Cu0.5) solder (then let sit for 24±2 hours for X5R, X6S, X7R, X7S, X7T, X7U and Y5V). Then apply a force in the direction shown in Fig.b. The soldering shall be done with the reflow method and shall be conducted with care so that the soldering is uniform and free of defects such as heat shock.																																
		(Unit in mm)  Fig. a.		<table border="1"> <thead> <tr> <th>Size</th> <th>a</th> <th>b</th> <th>C</th> </tr> </thead> <tbody> <tr> <td>0603</td> <td>0.3</td> <td>0.9</td> <td>0.3</td> </tr> <tr> <td>1005</td> <td>0.4</td> <td>1.5</td> <td>0.5</td> </tr> <tr> <td>1608</td> <td>1.0</td> <td>3.0</td> <td>1.2</td> </tr> <tr> <td>2012</td> <td>1.2</td> <td>4.0</td> <td>1.65</td> </tr> <tr> <td>3216</td> <td>2.2</td> <td>5.0</td> <td>2.0</td> </tr> <tr> <td>4520</td> <td>3.5</td> <td>7.0</td> <td>2.5</td> </tr> <tr> <td>4532</td> <td>3.5</td> <td>7.0</td> <td>3.7</td> </tr> </tbody> </table>  Fig. b.	Size	a	b	C	0603	0.3	0.9	0.3	1005	0.4	1.5	0.5	1608	1.0	3.0	1.2	2012	1.2	4.0	1.65	3216	2.2	5.0	2.0	4520	3.5	7.0	2.5	4532	3.5	7.0	3.7
Size	a	b	C																																	
0603	0.3	0.9	0.3																																	
1005	0.4	1.5	0.5																																	
1608	1.0	3.0	1.2																																	
2012	1.2	4.0	1.65																																	
3216	2.2	5.0	2.0																																	
4520	3.5	7.0	2.5																																	
4532	3.5	7.0	3.7																																	
12	Solderability of Termination	90% of the terminations are to be soldered evenly and continuously.		Immerse the test capacitor into a methanol solution containing rosin for 3 to 5 seconds, preheat it 150 to 180°C for 2 to 3 minutes and immerse it into SAC305(Sn96.5Ag3.0Cu0.5) solder of $245 \pm 5^\circ C$ for 3±1seconds.																																
13	Resistance to Soldering Heat	Appearance	No marking defects	*Preheat the capacitor at 120 to 150°C for 1 minute.																																
		Cap. Change	NP0 within $\pm 2.5\%$ or $0.25pF$ (whichever is larger)	Immerse the capacitor in a SAC305(Sn96.5Ag3.0Cu0.5) solder solution at $270 \pm 5^\circ C$ for 10 ± 1 seconds. Let sit at room temperature for 24±2 hours, then measure.																																
		Q/D.F.	If $C \leq 30pF$, DF $\leq 1/(400+20C)$ If $C > 30pF$, DF $\leq 0.1\%$	To satisfy the specified initial spec.																																
		I.R.	I.R. $\geq 10,000M\Omega$ or $R_c C_R \geq 500\Omega \cdot F$ (whichever is smaller)	* High dielectric constant type: Initial measurement : perform a heat treatment at $150 \pm 10^\circ C$ for one hour and then let sit for 24±2 hours at room temperature. Perform the initial measurement.																																

	Item	Specification		Test Method
		Temp. compensation type	High dielectric constant type	
14	Temperature cycle (Thermal shock)	Appearance	No marking defects	<p>Solder the capacitor to supporting jig (Glass epoxy board) and perform the five cycles according to the four heat treatments listed in the following table. Let sit for 24±2hrs at room temperature, then measure.</p> <p>Step 1: Minimum operating temperature 30±3min Step 2: Room temperature 2~3 min Step 3: Maximum operating temperature 30±3min Step 4: Room temperature 2~3min</p> <p>*High dielectric constant type: Initial measurement: perform a heat treatment at 150±10°C for one hour and then let sit for 24±2 hours at room temp. Perform the initial measurement.</p>
		Cap. Change	NPO within ±2.5% or 0.25pF (whichever is larger) X5R/X6S/X7R/X7S/X7T within ±7.5% X7U within ±30% Y5V within ±20%	
		Q/D.F.	If C≤30pF, DF≤1/(400+20C) If C>30pF, DF≤0.1%	
		I.R.	I.R. ≥ 10GΩ or R _C R ≥ 500Ω-F. (whichever is smaller)	
15	Humidity load	Appearance	No marking defects	<p>Apply the rated voltage at 40±2°C and 90 to 95% humidity for 500±12 hours. The charge / discharge current is less than 50mA.</p> <p>[Temperature compensation type] Remove and let sit for 24±2 hours at room temperature, then measure.</p> <p>[High dielectric constant type] *Initial measurement Perform a heat treatment at 150+0/-10°C for one hour and then let sit for 24±2 hours at room temperature. Perform the initial measurement. *Measurement after test Perform a heat treatment and then let sit for 24±2 hours at room temperature, then measure.</p>
		Cap. Change	NPO within ±7.5% or 0.75pF (whichever is larger) X5R/X6S/X7R/X7S/X7T/X7U within ±12.5% Y5V within ±30%	
		Q/D.F.	If C>30pF, DF≤0.5% If C≤30pF, DF≤1/(100+10xC/3) C in pF	
		I.R.	I.R. ≥ 500MΩ or R _C R ≥ 25Ω-F. (whichever is smaller)	
16	High temperature load life test	Appearance	No marking defects	<p>Apply 200% of the rated voltage for 1000±12 hours at the maximum operating temperature ± 3°C. The charge / discharge current is less than 50mA.</p> <p>[Temperature compensation type] Remove and let sit for 24±2 hours at room temperature, then measure.</p> <p>[High dielectric constant type] *Initial measurement Perform a heat treatment at 150+0/-10°C for one hour and then let sit for 24±2 hours at room temperature. Perform the initial measurement. *Measurement after test Perform a heat treatment and then let sit for 24±2 hours at room temperature, then measure.</p>
		Cap. Change	NPO within ±7.5% or 0.75pF (whichever is larger) X5R/X6S/X7R/X7S/X7T/X7U within ±12.5% Y5V within ±30%	
		Q/D.F.	If C>30pF, DF≤0.3% If 10pF<C≤30pF, DF≤1/(275+5xC/2) If C≤10pF, DF≤1/(200+10C), C in pF	
		I.R.	More than 1GΩ or R _C f ≥ 50Ω-F (whichever is less.)	

● General Purpose (II)

	Item	Specification	Test Method
1	Operation Temperature Range	X5R: -55 to 85 °C X6S: -55 to 105 °C X7R/X7S/X7T/X7U: -55 to 125 °C Y5V: -30 to 85 °C	---
2	Rated Voltage	Shown in the table of "Part Number & Characteristic"	The rated voltage is defined as the maximum voltage, which may be applied continuously to the capacitor.
3	Appearance	No defects or abnormalities.	Visual inspection
4	Dimensions	Within the specified dimension.	Using calipers
5	Dielectric Strength	No defects or abnormalities.	No failure shall be observed when 250% of the rated voltage is applied between the terminations for 1 to 5 seconds. The charge and discharge current is less than 50mA.
6	Insulation Resistance (I.R.)	$R_{IR} \geq 50\Omega \cdot F$	The insulation resistance shall be measured with a DC voltage not exceeding the rated voltage at 25°C and 75%RH max, and within 1 minute of charging, provided the charge/discharge current is less than 50 mA.
7	Capacitance	Within the specified tolerance * X5R, X6S, X7R, X7S, X7T, X7U and Y5V at 1000 hours	The capacitance / D.F. shall be measured at 25°C at the frequency and voltage shown in the table of "Part Number & Characteristic".
8	Q/Dissipation Factor (D.F.)	Shown in the table of "Part Number & Characteristic"	
9	Capacitance Temperature Characteristics	Capacitance change X5R/X7R within ±15%, X6S/X7S within ±22% X7U: -56% to + 22% X7T: -33% to + 22% Y5V: -82% to + 22%	The ranges of capacitance change compared with the 25°C value over the temperature ranges shall be within the specified ranges.
10	Termination Strength	No removal of the terminations or marking defect.	Apply a parallel force of 5N to a PCB mounted sample for 10±1sec. *2N for 0603 (EIA 0201).
11	Deflection (Bending Strength)	No cracking or marking defects shall occur at 1mm deflection. Capacitance change: X5R, X6S, X7R, X7S, X7T, X7U :within ±12.5% Y5V: within±20% (Unit in mm)  Fig. a.	Solder the capacitor to the test jig (glass epoxy boards) shown in Fig.a using a SAC305(Sn96.5Ag3.0Cu0.5) solder (then let sit for 24±2 hours for X5R, X6S, X7R, X7S, X7T, X7U and Y5V). Then apply a force in the direction shown in Fig.b. The soldering shall be done with the reflow method and shall be conducted with care so that the soldering is uniform and free of defects such as heat shock.  Fig. b.
12	Solderability of Termination	90% of the terminations are to be soldered evenly and continuously.	Immerse the test capacitor into a methanol solution containing rosin for 3 to 5 seconds, preheat it 150 to 180°C for 2 to 3 minutes and immerse it into SAC305(Sn96.5Ag3.0Cu0.5) solder of 245 ± 5°C for 3±1seconds.
13	Resistance to Soldering Heat	Appearance	No marking defects
		Cap. Change	X5R/X6S/X7R/X7S/X7T/X7U within ±7.5% Y5V within ±20%
		D.F.	To satisfy the specified initial spec.
		I.R.	$R_{IR} \geq 50\Omega \cdot F$.

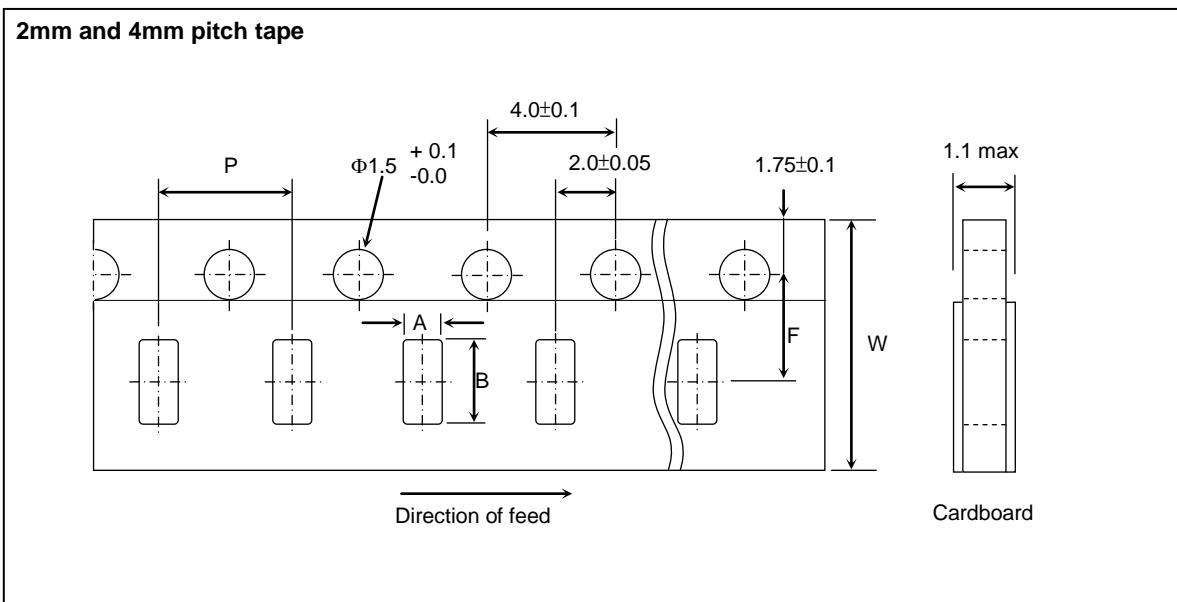
		Item	Specification	Test Method
14	Temperature cycle (Thermal shock)	Appearance	No marking defects	
		Cap. Change	X5R/X6S/X7R/X7S/X7T within $\pm 7.5\%$ X7U within $\pm 30\%$ Y5V within $\pm 20\%$	Solder the capacitor to supporting jig (Glass epoxy board) and perform the five cycles according to the four heat treatments listed in the following table. Let sit for 24 ± 2 hrs at room temperature, then measure.
		Q/D.F.	To satisfy the specified initial spec.	Step 1: Minimum operating temperature 30 ± 3 min Step 2: Room temperature 2~3 min Step 3: Maximum operating temperature 30 ± 3 min Step 4: Room temperature 2~3 min
		I.R.	I.R. $\geq 10G\Omega$ or $R_iC_R \geq 500\Omega\cdot F$. (whichever is smaller)	* Initial measurement: perform a heat treatment at $150\pm 10^\circ C$ for one hour and then let sit for 24 ± 2 hours at room temp. Perform the initial measurement.
15	Humidity load	Appearance	No marking defects	Apply the rated voltage at $40\pm 2^\circ C$ and 90 to 95% humidity for 500 ± 12 hours. The charge / discharge current is less than 50mA.
		Cap. Change	X5R/X6S/X7R/X7S/X7T/X7U within $\pm 12.5\%$ Y5V within $\pm 30\%$	*Initial measurement
		Q/D.F.	X5R/X6S/X7R/X7S/X7T/X7U 200% max of initial spec. Y5V 150% max of initial spec.	Perform a heat treatment at $150+0/-10^\circ C$ for one hour and then let sit for 24 ± 2 hours at room temperature.
		I.R.	I.R. $\geq 500M\Omega$ or $R_iC_R \geq 12.5\Omega\cdot F$. (whichever is smaller)	Perform the initial measurement. *Measurement after test Perform a heat treatment and then let sit for 24 ± 2 hours at room temperature, then measure.
16	High temperature load life test	Appearance	No marking defects	Apply 150% of the rated voltage for 1000 ± 12 hours at the maximum operating temperature $\pm 3^\circ C$. The charge / discharge current is less than 50mA.
		Cap. Change	X5R/X6S/X7R/X7S/X7T/X7U within $\pm 12.5\%$ Y5V within $\pm 30\%$	*Initial measurement
		D.F.	X5R/X6S/X7R/X7S/X7T/X7U 200% max of initial spec. Y5V 150% max of initial spec.	Perform a heat treatment at $150+0/-10^\circ C$ for one hour and then let sit for 24 ± 2 hours at room temperature.
		I.R.	More than $1G\Omega$ or $R_iC_R \geq 25\Omega\cdot F$ (whichever is less.)	Perform the initial measurement. *Measurement after test Perform a heat treatment and then let sit for 24 ± 2 hours at room temperature, then measure. * Some of the parts are applicable in rated voltage *100%. Please refer to "Part Number & Characteristic" with (II)* labeled in "Test Spec."

Package

- Tape and reel packaging**

Tape and reel packaging is currently the most promising system for high-speed production. A typical 180mm (7 inch) diameter reel contains 1,500 to 15,000 capacitors, 250mm (10 inch) contains 10,000 capacitors, and 330mm (13 inch) contains 10,000 to 50,000 capacitors. Three standard sizes are available in taped and reeled package either with paper carrier tapes or embossed tapes.

【Paper tape specifications】

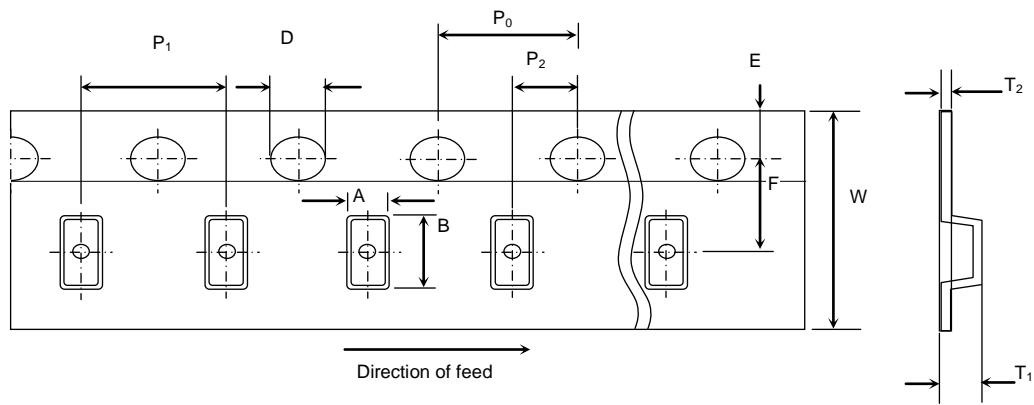


SYMBOL	PRODUCT SIZE CODE										UNIT	
	C0603(0201)		C1005(0402) Standard		C1005(0402) Special (1)		C1005(0402) Special (2)		C1005(0402) Special (3)			
	SIZE	TOL.	SIZE	TOL.	SIZE	TOL.	SIZE	TOL.	SIZE	TOL.		
A	0.38	± 0.04	0.65	± 0.10	0.70	± 0.10	0.72	± 0.10	0.80	± 0.10	mm	
B	0.68	± 0.04	1.15	± 0.10	1.19	± 0.10	1.25	± 0.10	1.35	± 0.10	mm	
F	3.5	± 0.05	3.5	± 0.05	3.5	± 0.05	3.5	± 0.05	3.5	± 0.05	mm	
P	2	± 0.10	2	± 0.10	2	± 0.10	2	± 0.10	2	± 0.10	mm	
W	8	± 0.20	8	± 0.20	8	± 0.20	8	± 0.20	8	± 0.20	mm	

SYMBOL	PRODUCT SIZE CODE (EIA)										UNIT	
	C1608(0603) Standard		C1608 (0603) Special (1)		C1608 (0603) Special (2)		C2012 (0805)		C3216 (1206)			
	SIZE	TOL.	SIZE	TOL.	SIZE	TOL.	SIZE	TOL.	SIZE	TOL.		
A	1.0	±0.2	1.0	±0.2	1.1	±0.2	1.5	±0.2	1.9	±0.2	mm	
B	1.8	±0.2	1.8	±0.2	1.9	±0.2	2.3	±0.2	3.6	±0.2	mm	
F	3.5	±0.05	3.5	±0.05	3.5	±0.05	3.5	±0.05	3.5	±0.05	mm	
P	4	±0.1	4	±0.1	4	±0.1	4	±0.1	4	±0.1	mm	
W	8	±0.2	8	±0.2	8	±0.2	8	±0.2	8	±0.2	mm	

【Embossed tape specifications】

1mm and 4mm and 8mm pitch tape

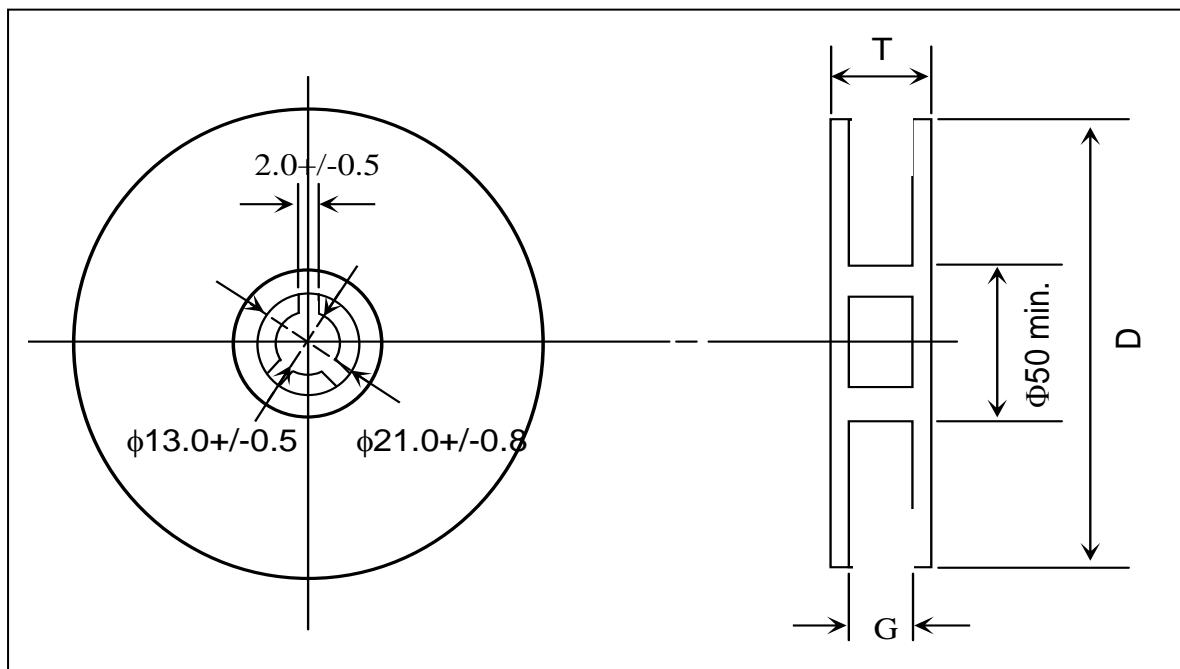


For $W=8\text{mm}$: $T_1=2.5\text{mm}$ max.

For $W=12\text{mm}$: $T_1=4.5\text{mm}$

DIMENSION (mm)	PRODUCT SIZE CODE					
	4 mm tape				8 mm tape	
	1608 (0603)	2012 (0805)	3216 (1206)	3225 (1210)	4520 (1808)	4532 (1812)
P_1	4 ± 0.1	4 ± 0.1	4 ± 0.1	4 ± 0.1	8 ± 0.1	8 ± 0.1
P_0	4 ± 0.1	4 ± 0.1	4 ± 0.1	4 ± 0.1	4 ± 0.1	4 ± 0.1
P_2	2 ± 0.05	2 ± 0.05	2 ± 0.05	2 ± 0.05	2 ± 0.05	2 ± 0.05
A	1.2 ± 0.2	1.45 ± 0.2	1.9 ± 0.2	2.8 ± 0.2	2.3 ± 0.2	3.6 ± 0.2
B	2.0 ± 0.2	2.3 ± 0.2	3.5 ± 0.2	3.6 ± 0.2	4.9 ± 0.2	4.9 ± 0.2
W	8 ± 0.3	8 ± 0.2	8 ± 0.2	8 ± 0.2	12 ± 0.2	12 ± 0.2
E	1.75 ± 0.1	1.75 ± 0.1	1.75 ± 0.1	1.75 ± 0.1	1.75 ± 0.1	1.75 ± 0.1
F	3.5 ± 0.05	3.5 ± 0.05	3.5 ± 0.05	3.5 ± 0.05	5.5 ± 0.05	5.5 ± 0.05
D	1.5 $(+0.1/-0.0)$	1.5 $(+0.1/-0.0)$	1.5 $(+0.1/-0.0)$	1.5 $(+0.1/-0.0)$	1.5 $(+0.1/-0.0)$	1.5 $(+0.1/-0.0)$
T_1	1.4 max.	2.5 max.	2.5 max.	2.5 max.	4.5	4.5
T_2	0.25 ± 0.1	0.305 ± 0.1	0.30 ± 0.1	0.30 ± 0.1	0.30 ± 0.1	0.30 ± 0.1

【Reel specifications】



TAPE WIDTH (mm)	G (mm)	T max. (mm)	D (mm)
4	5.0 ± 1.5	8.0	180
8	10.0 ± 1.5	14.5	180
8	10.0 ± 1.5	14.5	250
8	10.0 ± 1.5	14.5	330
12	14.0 ± 1.5	18.5	180

【Thickness and Packing Amount】

Thickness			Amount per reel			
			180 mm (7")		330 mm (13")	
Code	Spec.(mm)	Size (EIA)	Paper	Embossed	Paper	Embossed
Z	0.20	0402 (01005)	20K	40K ^{#1}		
A	0.30	0603 (0201)	15K		50K	
		1005 (0402)	15K		50K	
B	0.50	1005 (0402)	10K		50K	
Q	0.45	1005 (0402)	10K		50K	
		1608 (0603)	4K		15K	
C	0.60	2012 (0805)	4K		15K	
		3216 (1206)	4K		15K	
D	0.80	1608 (0603)	4K	4K	15K	
E	0.85	2012 (0805)	4K		15K	
		3216 (1206)	4K		15K	
		3225 (1210)		3K		10K
		4532 (1812)		1K		
I	0.95	2012 (0805)		3K		
		3216 (1206)		3K		
F	1.15	3216 (1206)		3K		10K
		4520 (1808)		3K		
G	1.25	2012 (0805)		2K/3K		10K
		3216 (1206)		3K		10K
		3225 (1210)		3K		
		4520 (1808)		2K/3K		
		4532 (1812)		1K		
		3225 (1210)		3K		
L	1.60	3216 (1206)		2K		
		3225 (1210)		2K		
		4520 (1808)		2K		
		4532 (1812)		1K		
N	2.00	3216 (1206)		2K/3K		
		3225 (1210)		1K/2K		
		4520 (1808)		1K		
		4532 (1812)		1K		
P	2.50	3225 (1210)		500pcs/1K		

#1: 4mm width 1mm pitch Embossed Taping

【Packing Rule】

EIA SIZE	Tape	Reel Size	Reels/Box	Boxes/ Carton
01005	Emboss	7"	8	12
01005	Paper	7"	5	12
0201	Paper	7"	5	12
0402	Paper	7"	5	12
0603	Paper/Emboss	7"	5	12
0805	Paper/Emboss	7"	5	12
1206	Paper/Emboss	7"	5	12
1210	Emboss	7"	5	12
1808	Emboss	7"	5	12
1812	Emboss	7"	5	12

Others

【Storage】

1. The chip capacitors shall be packaged in carrier tapes or bulk cases.
2. Keep storage place temperatures from +5°C to +35°C, humidity from 45 to 70% RH.
3. The storage atmosphere must be free of gas containing sulfur and chlorine. Also, avoid exposing the product to saline moisture. If the product is exposed to such atmospheres, the terminations will oxidize and solderability will be affected.
4. The solderability is assured for 12 months from our final inspection date if the above storage condition is followed.

【Circuit Design】

1. Once application and assembly environments have been checked, the capacitor may be used in conformance with the rating and performance, which are provided in both the catalog and the specifications. Exceeding the specifications listed may result in inferior performance. It may also cause a short, open, smoking, or flaming to occur, etc.
2. Please use the capacitors in conformance with the operating temperature provided in both the catalog and the specifications. Be especially cautious not to exceed the maximum temperature. In the situation the maximum temperature set forth in both the catalog and specifications is exceeded, the capacitor's insulation resistance may deteriorate, power may suddenly surge and short-circuit may occur. The loss of capacitance will occur, and may self-heat due to equivalent series resistance when alternating electric current is passed through. As this effect becomes critical in high frequency circuits, please exercise with caution. When using the capacitor in a (self-heating) circuit, please make sure the surface of the capacitor remains under the maximum temperature for usage. Also, please make certain temperature rise remain below 20°C.
3. Please keep voltage under the rated voltage, which is applied to the capacitor. Also, please make certain the peak voltage remains below the rated voltage when AC voltage is super-imposed to the DC voltage. In the situation where AC or pulse voltage is employed, ensure average peak voltage does not exceed the rated voltage. Exceeding the rated voltage provided in both catalog and specifications may lead to defective withstanding voltage or, in worse case situations, may cause the capacitor to burn out.
4. It's a common phenomenon of high-dielectric products to have a deteriorated amount of static electricity due to the application of DC voltage.

【Handling】

Chip capacitors should be handled with care to avoid contamination or damage. The use of vacuum pick-up or plastic tweezers is recommended for manual placement. Tape and reeled packages are suitable for automatic pick and placement machine.

【Flux】

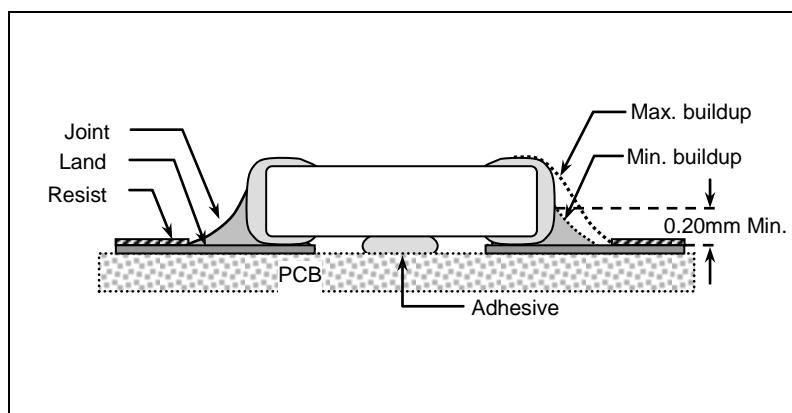
1. An excessive amount of flux or too rapid temperature rise can cause solvent burst, solder can generate a large quantity of gas. The gas can spread small solder particles to cause solder balling effect or bridging problem.
2. Flux containing too high of a percentage of halide may cause corrosion of termination unless sufficient cleaning is applied.
3. Use rosin-type flux. Highly acidic flux (halide content less than 0.2wt%) is not recommended.
4. The water soluble flux causes deteriorated insulation resistance between outer terminations unless sufficiently cleaned.

【Component Spacing】

For wave soldering components, the spacing must be sufficient far apart to prevent bridging or shadowing. This is not so important for reflow process but enough space for rework should be considered. The suggested spacing for reflow soldering and wave soldering is 0.5mm and 1.0mm, respectively.

【Solder Fillet】

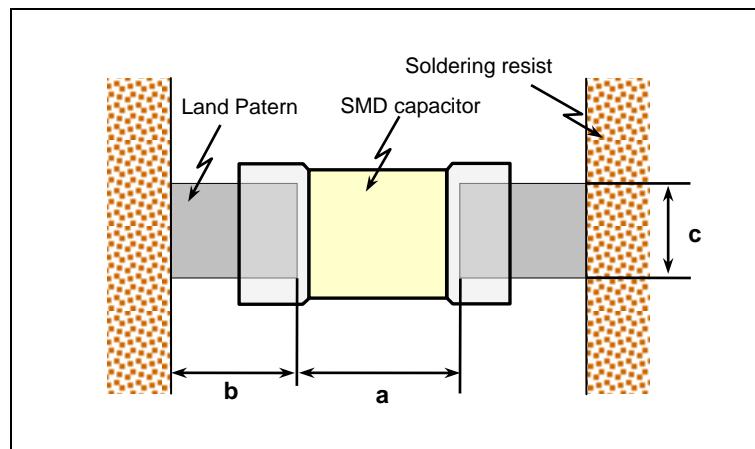
Too much solder amount may increase solder stress and cause crack risk. Insufficient solder amount may reduce adhesive Strength and cause parts falling off PCB. When soldering, confirm that the solder is placed over 0.2mm of the surface of the terminations.



【Recommended Land Pattern Dimensions】

When mounting the capacitor to substrate, it's important to consider that the amount of solder (size of fillet) used has a direct effect upon the capacitor once it's mounted.

1. The greater the amount of solder, the greater the stress to the elements, as this may cause the substrate to break or crack.
2. In the situation where two or more devices are mounted onto a common land, separate the device into exclusive pads by using soldering resist.
3. Land width equal to or less than component. It is permissible to reduce land width to 80% of component width.



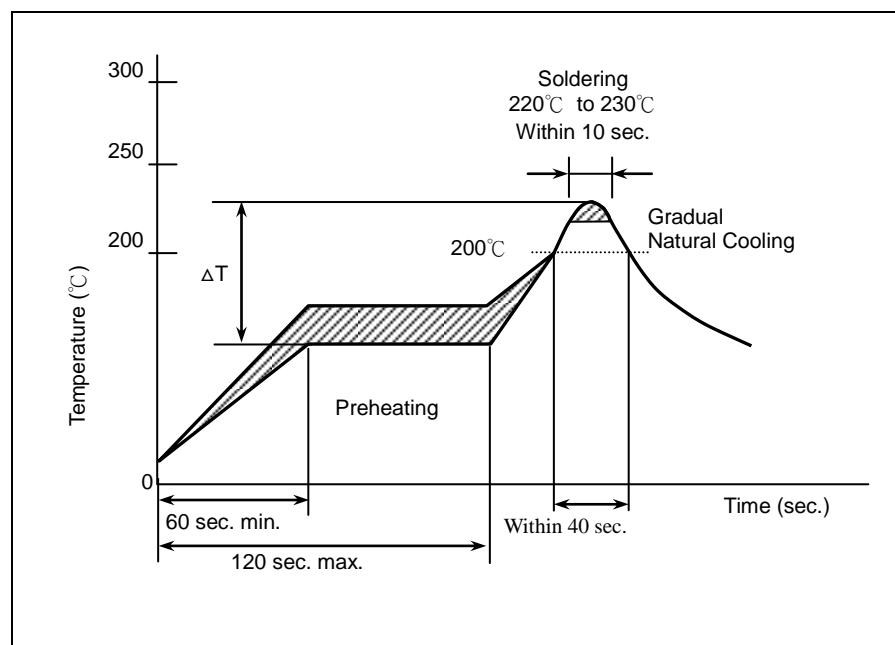
Size mm (EIA)	L x W (mm) (Dimension tolerance)	a (mm)	b (mm)	c (mm)
0402 (01005)	0.4*0.2	0.16 to 0.20	0.12 to 0.18	0.20 to 0.23
0603 (0201)	0.6*0.3	0.15 to 0.35	0.2 to 0.3	0.25 to 0.3
1005 (0402)	1.0*0.5 (within ± 0.10)	0.3 to 0.5	0.35 to 0.45	0.4 to 0.5
	1.0*0.5 (± 0.15 or ± 0.20)	0.4 to 0.6	0.4 to 0.5	0.5 to 0.6
1608 (0603)	1.6*0.8 (within ± 0.10)	0.7 to 1.0	0.6 to 0.8	0.7 to 0.8
	1.6*0.8 (± 0.15 or ± 0.20)	0.8 to 1.1	0.7 to 0.9	0.8 to 0.9
2012 (0805)	2.0*1.25	1.0 to 1.3	0.7 to 0.9	1.0 to 1.2
3216 (1206)	3.2*1.6	2.1 to 2.5	1.0 to 1.2	1.3 to 1.6
3225 (1210)	3.2*2.5	2.1 to 2.5	1.0 to 1.2	2.0 to 2.5
4520 (1808)	4.5*2.0	3.2 to 3.8	1.2 to 1.4	1.7 to 2.0
4532 (1812)	4.5*3.2	3.2 to 3.8	1.2 to 1.4	2.7 to 3.2

【Resin Mold】

If a large amount of resin is used for molding the chip, cracks may occur due to contraction stress during curing. To avoid such cracks, use a low shrinkage resin. The insulation resistance of the chip will degrade due to moisture absorption. Use a low moisture absorption resin. Check carefully that the resin does not generate a decomposition gas or reaction gas during the curing process or during normal storage. Such gases may crack the chip capacitor or damage the device itself.

【Soldering Profile for SMT Process with SnPb Solder Paste】

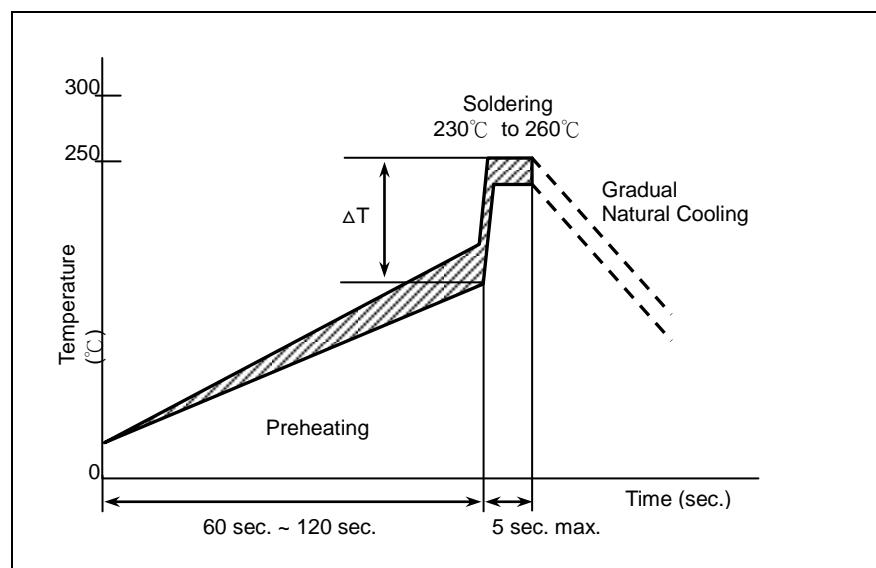
Reflow Soldering



The difference between solder and chip surface should be controlled as following table. The rate of preheat should not exceed 4°C/sec and a target of 2°C/sec is preferred.

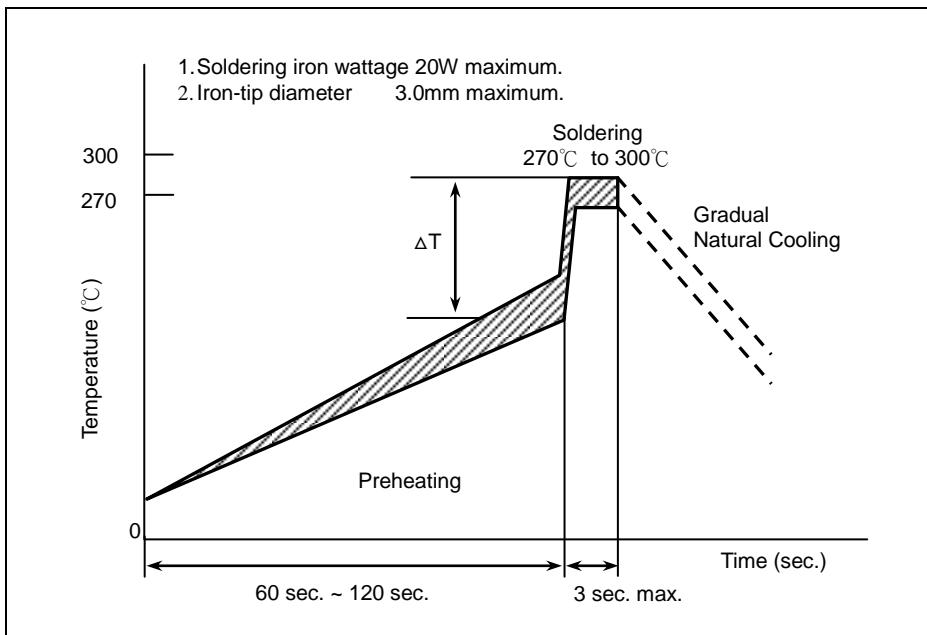
Chip Size	3216 and smaller	3225 and above
Preheating	$\Delta T \leq 150^{\circ}\text{C}$	$\Delta T \leq 130^{\circ}\text{C}$

Wave Soldering



Chip Size	3216 and smaller	3225 and above
Preheating	$\Delta T \leq 150^\circ\text{C}$	-

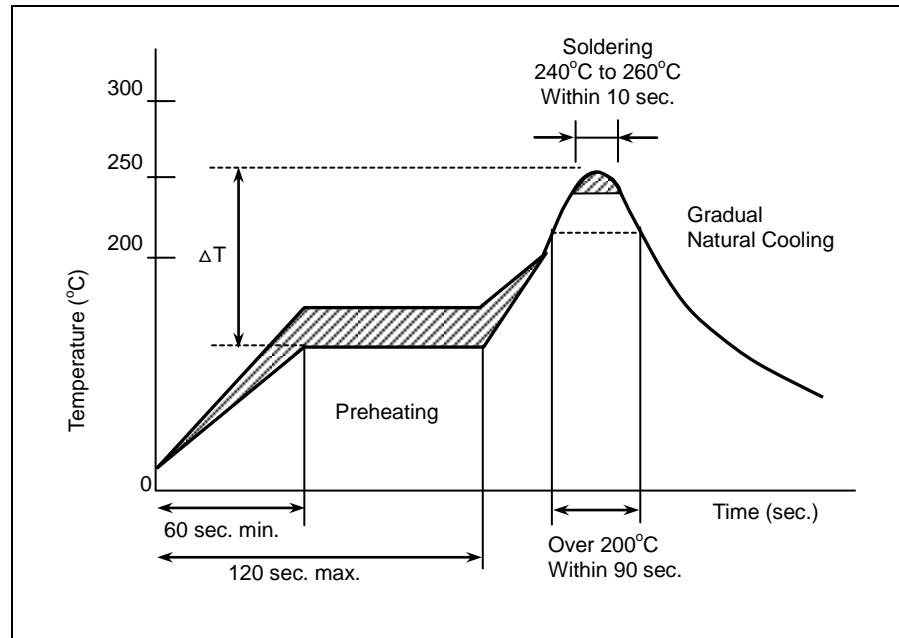
Soldering Iron



Chip Size	3216 and smaller	3225 and above
Preheating	$\Delta T \leq 190^\circ\text{C}$	$\Delta T \leq 130^\circ\text{C}$

【Soldering】

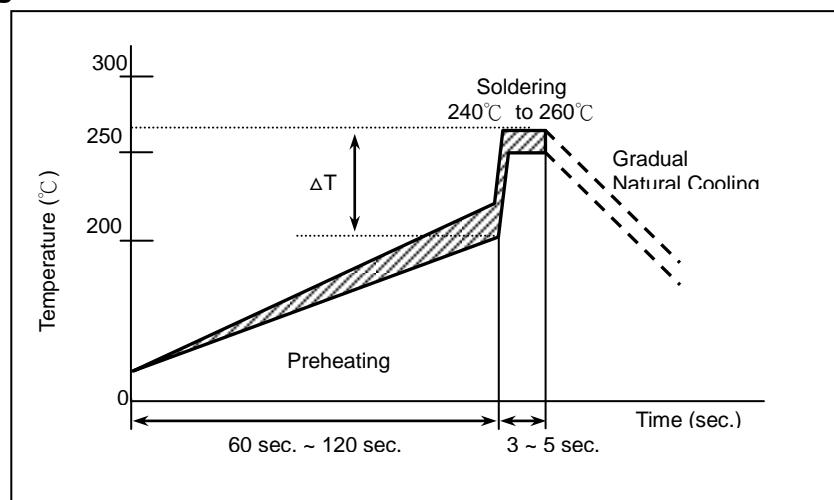
Reflow Soldering for Lead free Termination



The difference between solder and chip surface should be controlled as following table. The rate of preheat should not exceed 4°C/sec and a target of 2°C/sec is preferred.

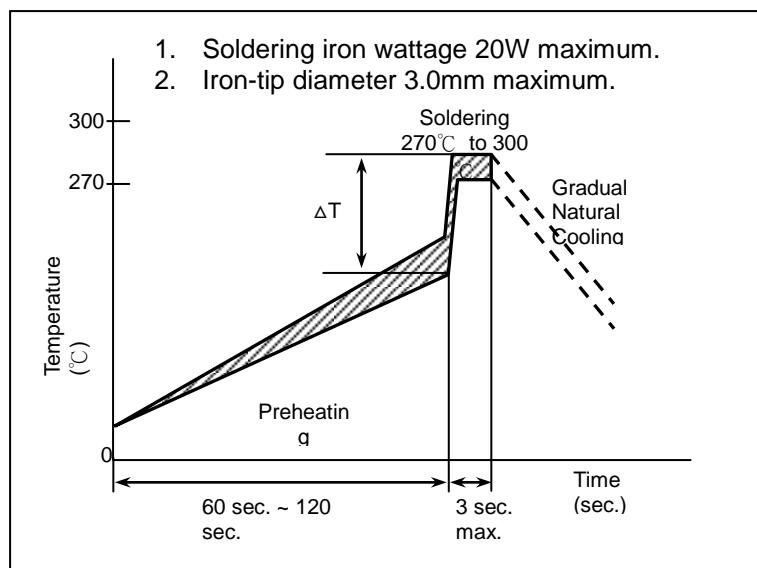
Chip Size	3216 and smaller	3225 and above
Preheating	$\Delta T \leq 150^\circ\text{C}$	$\Delta T \leq 130^\circ\text{C}$

Flow Soldering for Lead free Termination



Chip Size	3216 and smaller	3225 and above
Preheating	$\Delta T \leq 150^\circ\text{C}$	-

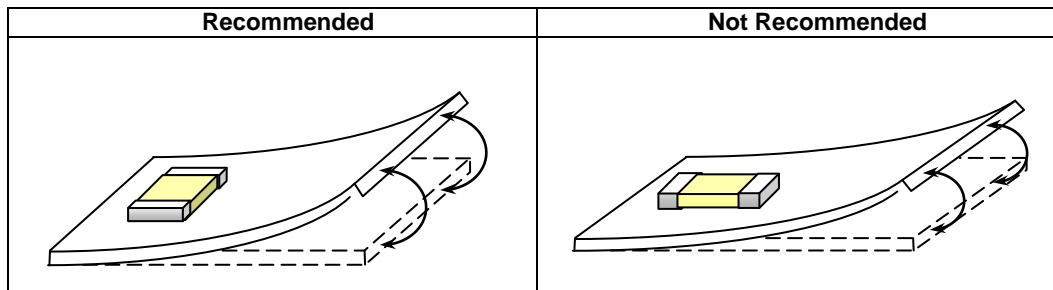
Soldering Iron



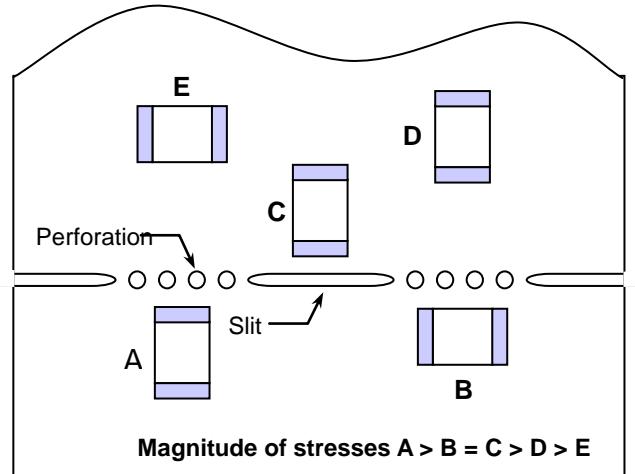
Chip Size	3216 and smaller	3225 and above
Preheating	$\Delta T \leq 190^\circ\text{C}$	$\Delta T \leq 130^\circ\text{C}$

【Chip Layout and Breaking PCB】

- To layout the SMD capacitors for reducing bend stress from board deflection of PCB. The following are examples of Hood and bad layout.

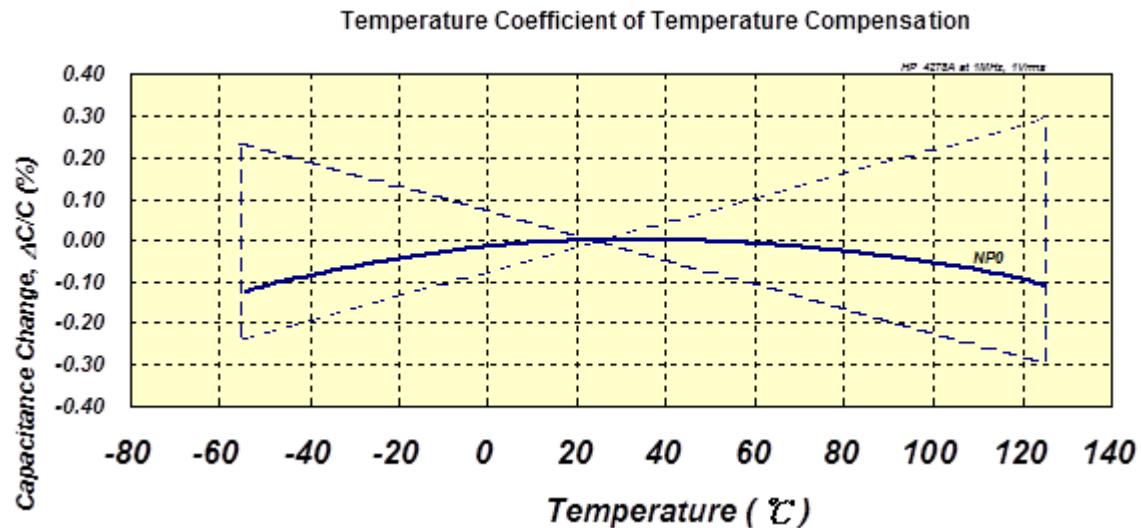


- When breaking PCB, the layout should be noted that the mechanical stresses are depending on the position of capacitors. The following example shows recommendation for better design.

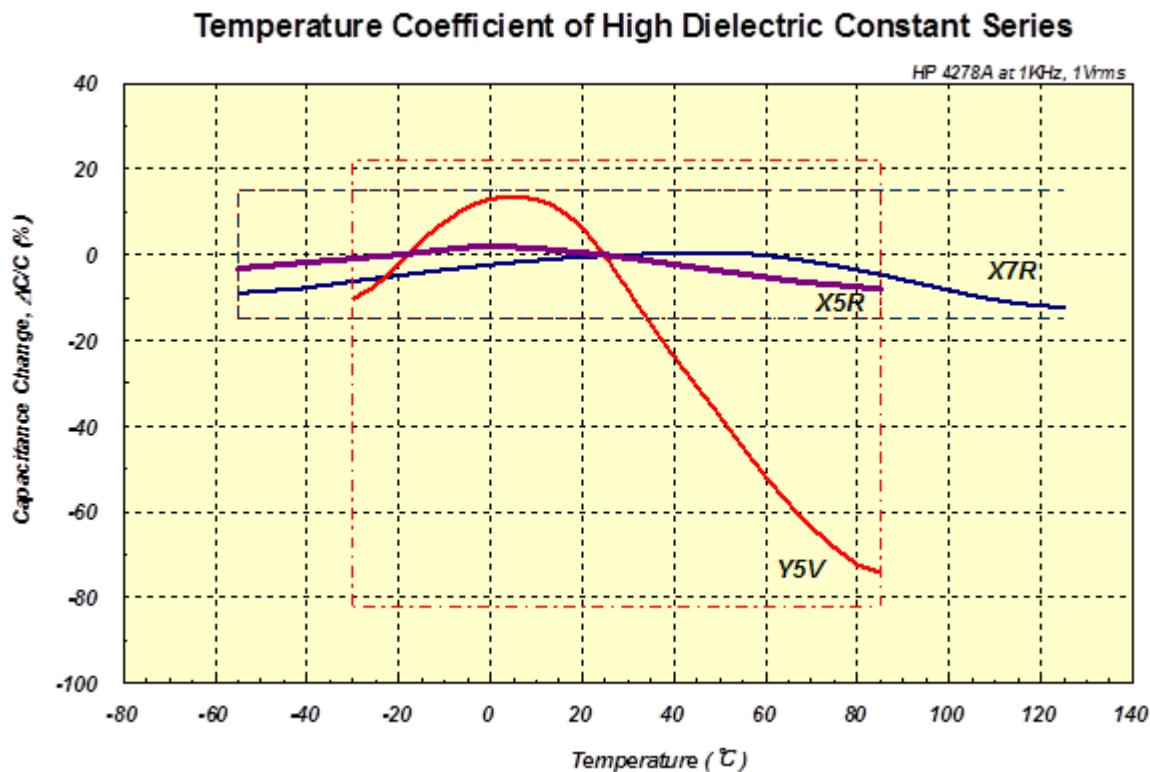


【Temperature Coefficient】

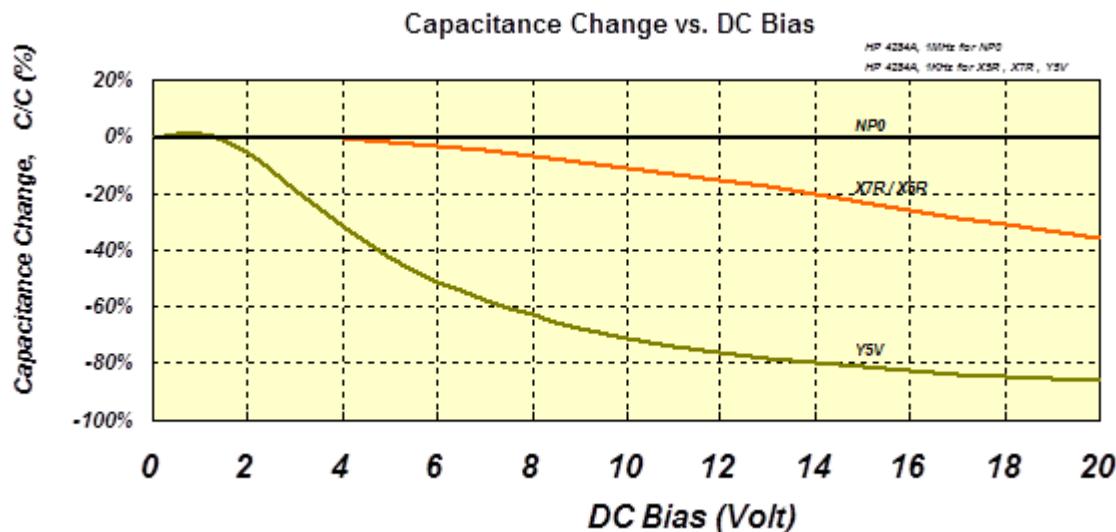
- Class 1 (Temperature Compensation series)



- Class 2 (High Dielectric Constant Series)

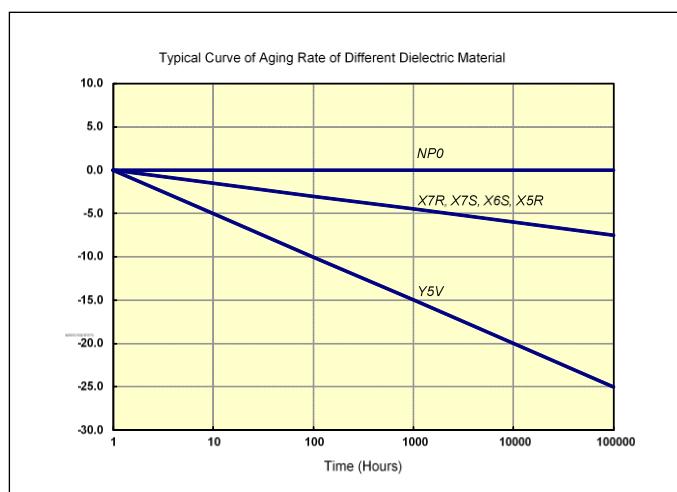


【DC Voltage Coefficient】



【Aging Rate】

The capacitance and dissipation factor of class 2 capacitors decreases with time. It is known as 'aging' that follows a logarithmic law and expressed in terms of an aging constant. Aging is caused by a gradual re-alignment of the crystalline structure of the ceramic. The aging constant is defined as the percentage loss of capacitance at a 'time decade'. The law of capacitance aging is expressed as following equation:



$$C_{t2} = C_{t1} \times (1 - k \times \log_{10}(t_2/t_1))$$

C_{t1} : Capacitance after t_1 hours of start aging.

C_{t2} : Capacitance after t_2 hours of start aging.

k : aging constant (capacitance decrease per decade)

t_1, t_2 : time in hours from start of aging.

A typical curve of aging rate is shown in following figure.

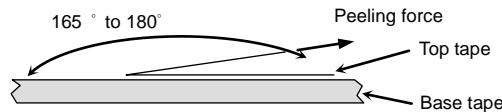
When heating the capacitors above Curie temperature ($130^{\circ}\text{C} \sim 150^{\circ}\text{C}$) the capacitance can be re-new. So capacitance of class 2 capacitors will be complete de-aged by soldering process; subsequently a new aging process begins.

Because of aging, it is specified an age for measurement to meet the prescribed tolerance for class 2 capacitors. Normally, 1000 hours ($t_2=1000$ hrs) is defined.

【Peeling Off Force】

Peeling off force: 0.1N to 1.0 N* in the direction shown as below.

The peeling speed: 300±10 mm/min



1. The taped tape on reel is wound clockwise. The sprocket holes are to the right as the tape is pulled toward the user.
2. There are minimum 150 mm as the leader and minimum 40 mm empty tape as the tail is attached to the end of the tape.